



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-10-25
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDA14V2SC6Y	CDWB*EAY14V5	A	ZS1A	2016-10-25
Amount		UoM	Unit type	ST ECOPACK Grade
16		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.8 - 1.5 - 0.9	6	gull wing	
Comment	Package: SOT 23 - 6L			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CDWB*EAY14V5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.689	mg	supplier	die	Silicon (Si)	7440-21-3		0.594	mg	862119	37125
				supplier	metallization	Aluminium (Al)	7429-90-5		0.081	mg	117562	5063
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	10160	438
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	1451	63
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1451	63
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	7257	313
Lead-frame	Other inorganic materials	6.934	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.697	mg	965821	418563
				supplier	alloy	Iron (Fe)	7439-89-6		0.156	mg	22498	9750
				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	288	125
				supplier	alloy	Zinc (Zn)	7440-66-6		0.009	mg	1298	563
				supplier	metallization	Silver (Ag)	7440-02-0		0.070	mg	10095	4375
				supplier	glue	Silver (Ag)	7440-22-4		0.046	mg	696970	2875
Die Attach	Other inorganic materials	0.066	mg	supplier	glue	methylene diacrylate	42594-17-2		0.016	mg	242424	1000
				supplier	glue	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.002	mg	30303	125
				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.002	mg	30303	125
				supplier	wire	Copper (Cu)	7440-50-8		0.152	mg	980645	9500
Bonding wire	Other inorganic materials	0.155	mg	supplier	wire	Palladium (Pd)	7440-05-3		0.003	mg	19355	188
				supplier	wire	Palladium (Pd)	7440-05-3		0.003	mg	19355	188
Encapsulation	Other inorganic materials	7.766	mg	supplier	mold compound	Silica, vitreous	60676-86-0		6.622	mg	852691	413875
				supplier	mold compound	phenolic resin	29690-82-2		0.273	mg	35153	17063
				supplier	mold compound	epoxy resin	25068-38-6		0.311	mg	40046	19438
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.155	mg	19959	9682
				supplier	mold compound	carbon black	1333-86-4		0.016	mg	2061	1000
				supplier	mold compound	Zinc hydroxide	20427-58-1		0.078	mg	10044	4875
Connections coating	Solder	0.390	mg	supplier	mold compound	Magnesium hydroxide	1309-42-8		0.311	mg	40046	19438
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.390	mg	1000000	24375